

Title (en)
METHOD FOR PRODUCING BOND PADS ON A PRINTED CIRCUIT

Title (de)
VERFAHREN ZUR HERSTELLUNG VON ANSCHLUSSHÖCKERN AUF EINER LEITERPLATTE

Title (fr)
PROCEDE DE REALISATION DE PLOTS DE CONNEXION SUR UN CIRCUIT IMPRIME

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Application
EP 01989644 A 20011220

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• FR 0104117 W 20011220
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Abstract (en)
[origin: WO02054842A1] The invention concerns a method for producing a chromium coating (4) so that the material of the bond pad (8) remains in a zone totally limited by the chromium coating (4). The invention is applicable to bond pads for electronic components.

IPC 1-7
H05K 3/34; **H01L 21/60**; **H01L 21/48**

IPC 8 full level
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CPC (source: EP KR US)
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